

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
120V	5.4mΩ@10V	90A
	6.6mΩ@4.5V	

Feature

- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested
- Optimized for High Speed Smooth Switching

Application

- Power Switching Application
- DC/DC Converters

MARKING:



T054N12L = Device Code

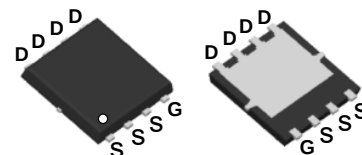
XX = Date Code

Solid Dot = Green Indicator

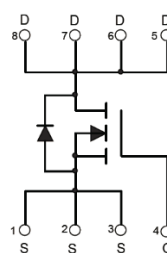
ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain - Source Voltage		V _{DS}	120	V
Gate - Source Voltage		V _{GS}	±20	V
Continuous Drain Current ¹	T _C = 25℃	I _D	90	A
	T _C = 120℃	I _D	57	A
Pulsed Drain Current ²		I _{DM}	360	A
Single Pulsed Avalanche Current ³		I _{AS}	35	A
Single Pulsed Avalanche Energy ³		E _{AS}	245	mJ
Power Dissipation ⁵	T _C = 25℃	P _D	118	W
Thermal Resistance from Junction to Ambient ⁶		R _{θJA}	56	℃/W
Thermal Resistance from Junction to Case		R _{θJC}	1.06	℃/W
Junction Temperature		T _J	150	℃
Storage Temperature		T _{STG}	-55~ +150	℃

PDFN5X6-8L



Schematic diagram



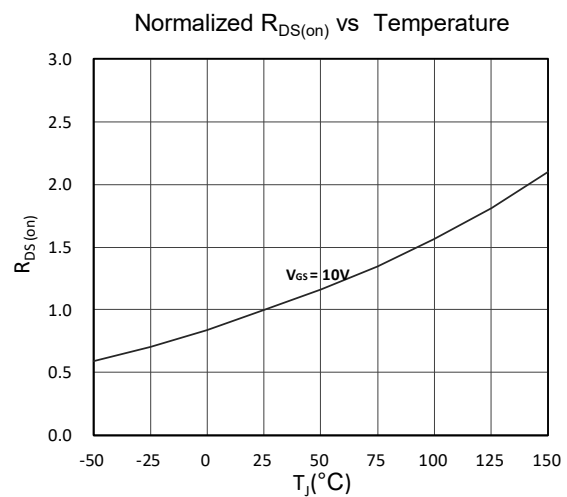
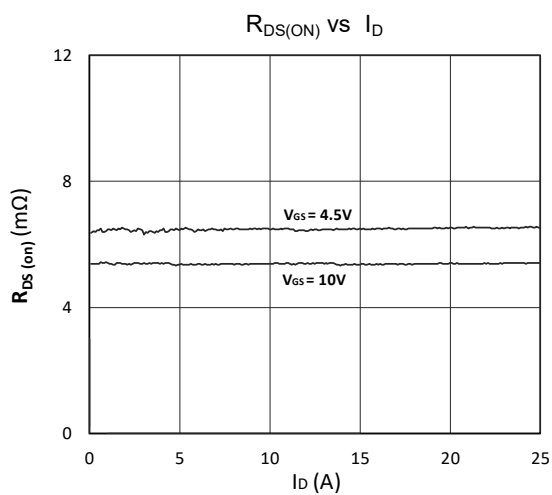
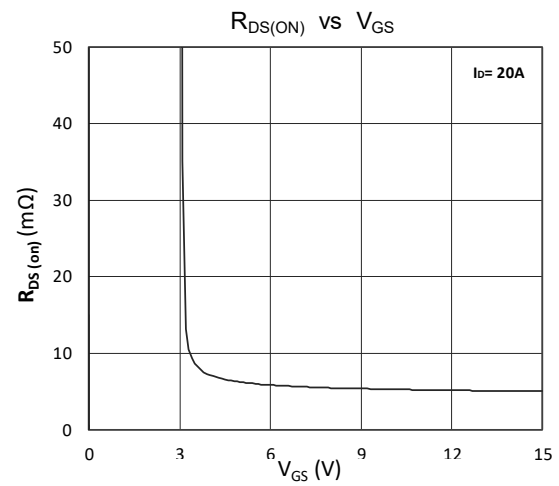
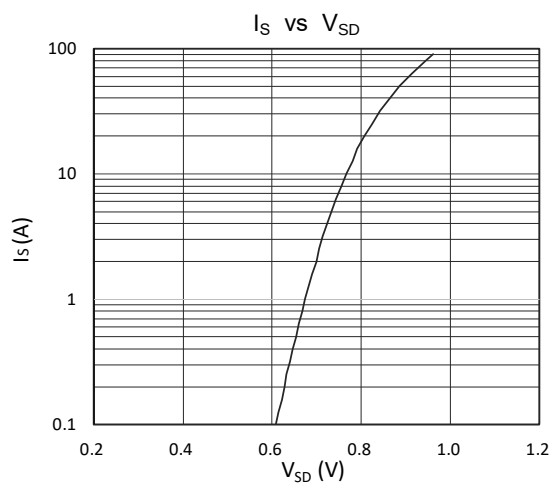
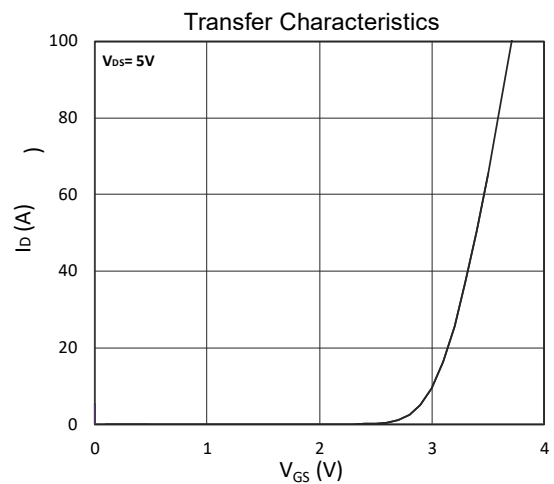
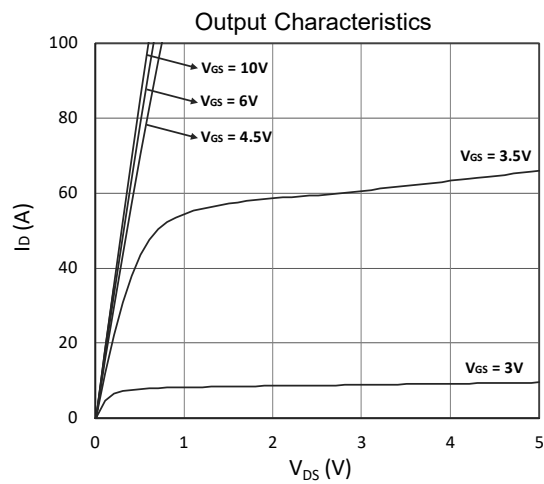
MOSFET ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

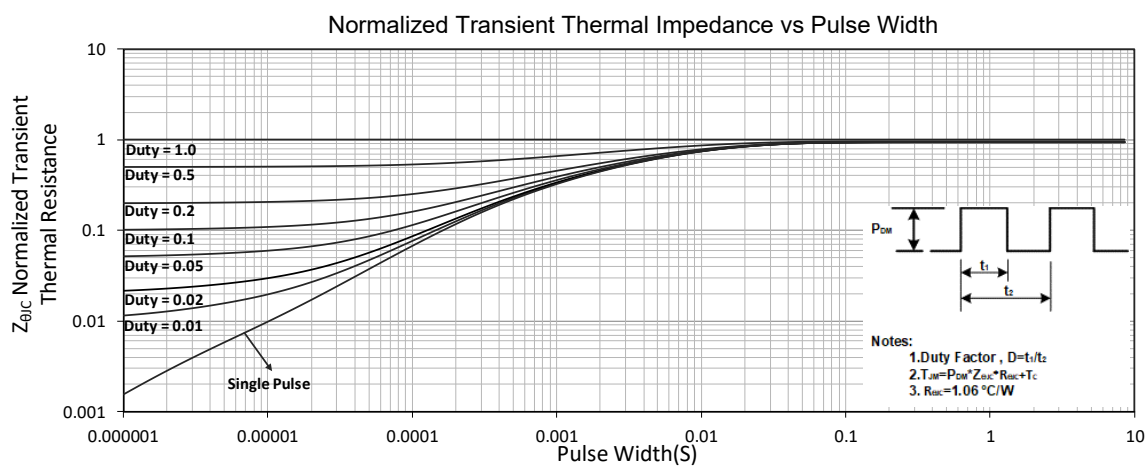
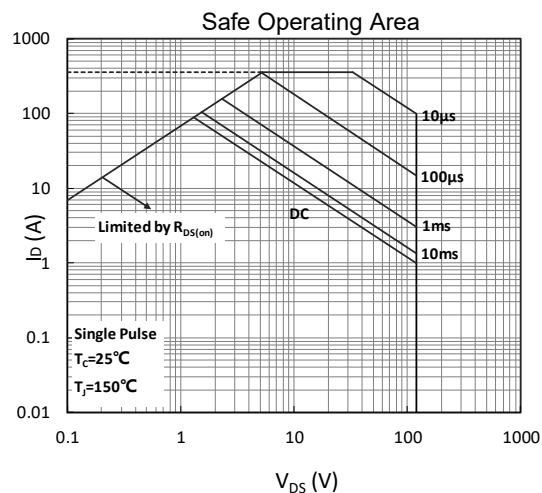
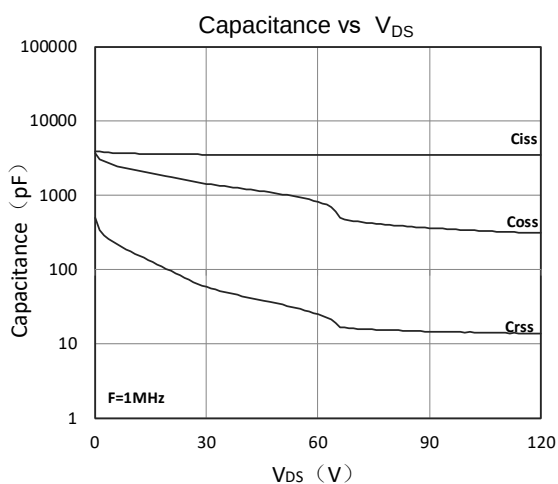
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	120			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 120V, V _{GS} = 0V			1	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics ⁴						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1	2	3	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A		5.4	7.0	mΩ
		V _{GS} = 4.5V, I _D = 20A		6.6	9.0	
Forward Transconductance	g _{FS}	V _{DS} = 10V, I _D = 20A		92		S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 60V, V _{GS} = 0V, f = 1MHz		3415		pF
Output Capacitance	C _{oss}			520		
Reverse Transfer Capacitance	C _{rss}			12		
Gate Resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		3		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} = 60V, V _{GS} = 10V, I _D = 20A		53		nC
Gate-source Charge	Q _{gs}			10		
Gate-drain Charge	Q _{gd}			9.5		
Turn-on Delay Time	t _{d(on)}	V _{DD} = 60V, V _{GS} = 10V, I _D = 20A, R _G = 3Ω		12		ns
Turn-on Rise Time	t _r			10		
Turn-off Delay Time	t _{d(off)}			52		
Turn-off Fall Time	t _f			19		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	V _{GS} = 0V, I _S = 20A			1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F =20A, dI _F /dt=500A/μs		66		ns
Body Diode Reverse Recovery Charge	Q _{rr}			113		nC

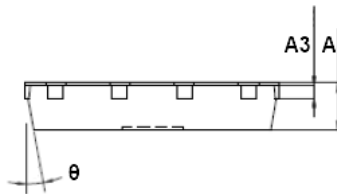
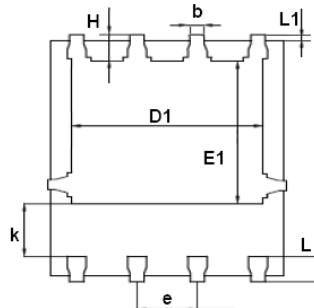
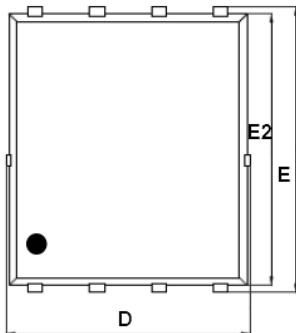
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width ≤ 10μs, duty cycle ≤ 1%.
- 3.EAS condition: V_{DD} = 25V, V_{GS} = 10V, L = 0.4mH, R_G = 25Ω Starting T_J = 25°C.
- 4.Pulse Test : Pulse Width ≤ 300μs, duty cycle ≤ 2%.
- 5.The power dissipation P_D is limited by T_{J(MAX)} = 150°C.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.

Typical Characteristics





PDFN5X6-8L Package Information


SYMBOL	MM	
	MIN	MAX
A	0.90	1.20
A3	0.15	0.35
D	4.80	5.40
E	5.90	6.35
D1	3.61	4.31
E1	3.30	3.92
E2	5.50	6.06
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.71
θ	0°	12°